



Docket No.: M4065.0248/P248-C  
(PATENT)

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

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In re Patent Application of:  
Allen McTeer

Application No.: 10/656,182

Art Unit: 2815

Filed: September 8, 2003

Examiner: E. Lee

For: A MULTI-LAYERED COPPER BOND PAD  
FOR AN INTEGRATED CIRCUIT

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**AMENDMENT IN RESPONSE TO NON-FINAL OFFICE ACTION**

MS Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

**INTRODUCTORY COMMENTS**

In response to the Office Action dated September 8, 2004 (Paper No. 20040717), please amend the above-identified U.S. patent application as follows:

**Amendments to the specification** begin on page 3 of this paper.

**Amendments to the Claims** are reflected in the listing of claims which begins on page 5 of this paper.

**Amendments to the Drawings** begin on page 7 of this paper.

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Reply to Office Action dated September 8, 2004

**Remarks** begin on page 8 of this paper.